

LIQUID RESIN COMPOSITION, SEMICONDUCTOR CHIP WITH AN ADHESIVE LAYER, METHOD OF PRODUCING SUCH MATERIALS, AND SEMICONDUCTOR DEVICES

ABSTRACT OF THE DISCLOSURE

A liquid resin composition includes (A) an epoxy resin component and (B) a curing agent component, the epoxy resin component (A) being liquid at room temperature, and the curing agent component (B) including (B1) a compound which has phenolic hydroxyl group(s) and is dissolvable in the epoxy resin component (A), and (B2) a compound which has hydroxyl group(s) and is not dissolvable in the epoxy resin component (A).

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NO FIGURE